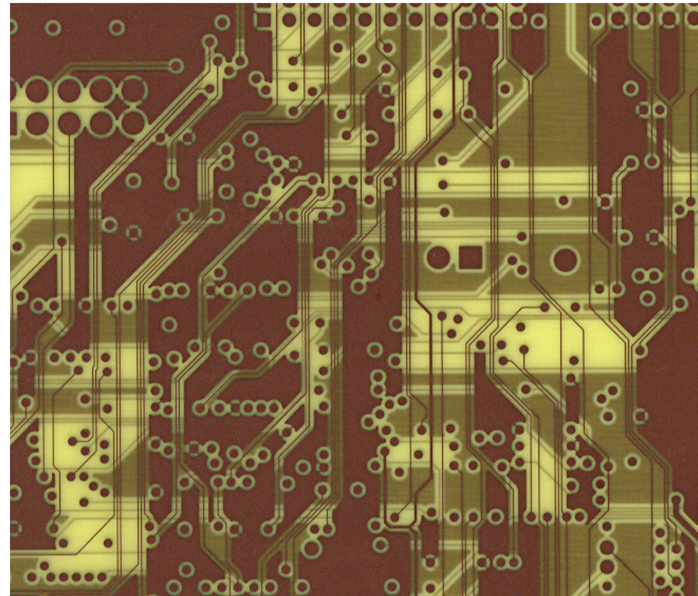
MultiBond MP

Innerlayer Bonding System

The No-Risk Oxide Alternative from the Market Leader in Innerlayer Bonding.



MacDermid Enthone's **MultiBond MP** is the leading technology for innerlayer adhesion promotion designed specifically to perform at the high temperatures required for today's lead-free soldering of circuit boards. An exceptional alternative to oxide whose chemistry is compatible with all existing equipment, MultiBond MP is supported by MacDermid Enthone's renowned on-site service.

MultiBond MP, trusted by over 250 customers worldwide, now offers a superior innerlayer bonding process with significantly higher copper capacity and sludge-free operation. Able to withstand the intense thermal stress that results from lead free processing, it improves reliability on high layer count designs. As a part of our on-going program of innovation in oxide alternative technology, the MultiBond MP family is the right choice for critical multilayer applications.

KEY FEATURES

- Optimum adhesion promoter for bonding multilayer circuit boards
- Installed base of over 250 customers worldwide
- Higher copper-carrying capacity results in less solid waste
- Best results on advanced dielectrics
- Compatible with existing equipment

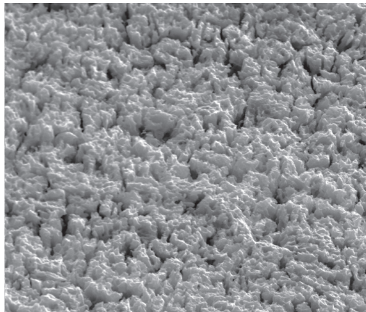
MacDermid Enthone

MultiBond MP

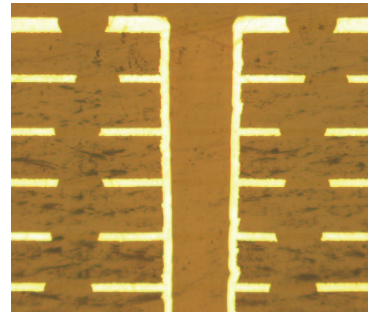
Innerlayer Bonding System

Superior Bonding for Multilayer Adhesion.

As the market leader in alternative oxide, MacDermid Enthone has designed the best coating chemistry for your application. MultiBond MP enables consistently high bond strengths to high Tg epoxy, PTFE, polyimide, BT, and non-halogenated resins. And our technical experts can help you make a seamless transition to lead-free assembly. Special features of our superior chemistry include lower etch for controlled impedance, minimal wedge attack, high copper loading (>40 grams/liter) and clean, sludge-free processing. Able to increase productivity while reducing overall costs, MultiBond MP is the right choice in oxide alternative.

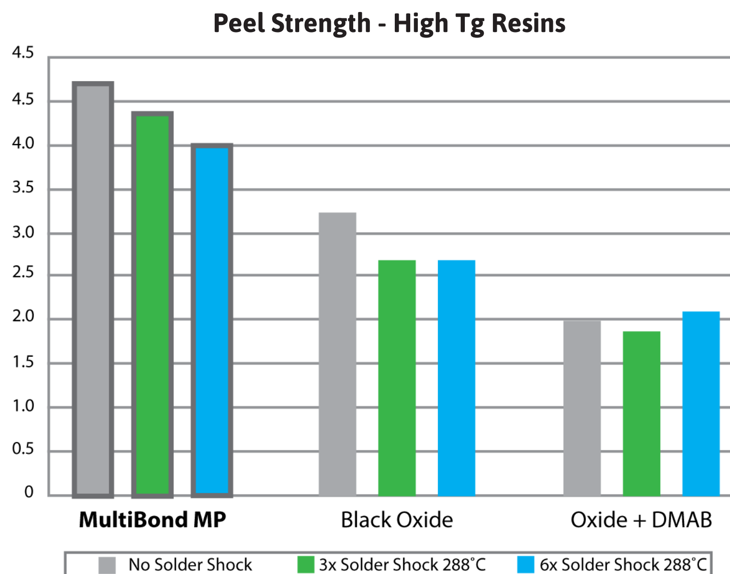


Typical SEM at 5000x of MultiBond MP surface showing superior topography for bonding to resin prepregs



4x sequential lamination multilayer subsequently processed through 3x lead-free reflow and soldershocked 3x @ 260°C for assembly rework simulation. No delamination.

MultiBond MP Peel vs Conventional Oxide



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